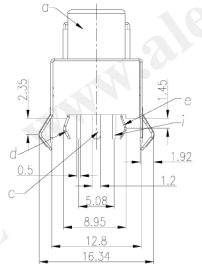
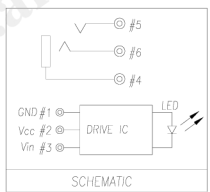
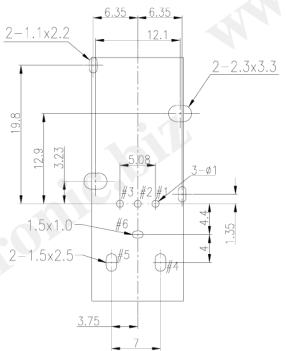
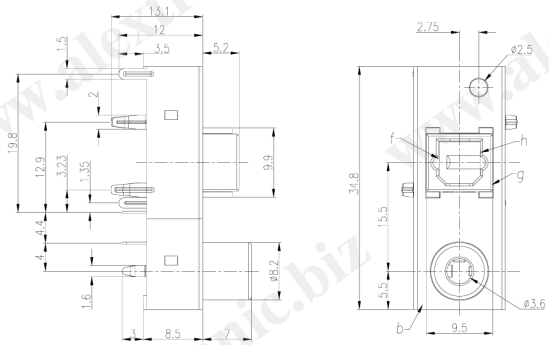


CATEGORY	DESCRIPTION	P/N #
CONNECTOR	3.5 Phone Jack+Toslink, V/A, 1/1H, With Shielding, Without Switch	AT850V-12160-000T

REV.	ECN NO	DESCRIPTION	REVISED	DATE
R01		NEW RELEASE	XSX	2009.08.05



RECOMMEND PCB LAYOUT
(TOP VIEW)(TOLERANCE:±0.05)
PCB THICKNESS:1.6mm

- PHONE JACK SPECIFICATION
1. Voltage Rating: DC 30V Min.
 2. Current Rating: 1.0A Max.
 3. Contact resistance: 30mΩ Max.
 4. Insulation resistance: 100MΩ Min. (DC250V)
 5. Operation Temperature: -25°C~70°C
 6. Withstand Voltage: AC500V
 7. Insertion force: 3kgf Max.
 8. Extraction force: 0.3kgf Min.
 9. life testing: 3,000 cycles
 10. To conform with the "QC-03-045"& "RoHS DIRECTIVE"
 11. Solder heat resistance: wave soldering 260°C 5 seconds

- TOSLINK SPECIFICATION
1. Voltage Rating: Vcc=0.5~7V, Vin=-0.5~7.5V
 2. Current Rating: 25mA
 3. Insertion Force: 2.5Kgf Max.
 4. Extraction Force: 0.5Kgf Min.
 5. Life test: 1,500 cycles
 6. Temperature Range: -20°C~70°C
 7. To conform with the "QC-03-045"& "RoHS DIRECTIVE"
 8. Solder heat resistance: wave soldering 260°C 5 seconds

i	ODL	1		16Mbps	
h	Spring	1	SUS		
g	Frame	1	PA66 UL94V-0	Black	
f	Gate	1	PA66 UL94V-2	Lime(#577C)	
e	Terminal#6	1	Phosphor Bronze, T=0.3mm	CuSn Plating	
d	Terminal#5	1	Phosphor Bronze, T=0.3mm	CuSn Plating	
c	Terminal#4	1	Phosphor Bronze, T=0.3mm	CuSn Plating	
b	Shielding	1	BRASS T=0.3mm	CuSn Plating	
a	Housing	1	PBT UL94V-0	Black	
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR	REMARK

Product Drawing
ALEXTRONIC

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1	UNIT: mm	⊕ ⊖ DWG.NO:
	SIZE: A3	PAGE:1 OF 1	REV:R01 WI-061-548
DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2	ANGLES: X :±2° X.X :±1°	APPROVED BY	CHECKED BY
		WYX	Pengjie
			PREPARED BY XSX
CUSTOMER COPY			